



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20200507000.1**

**Qualification of TI Malaysia an additional Assembly site for Select Devices  
Change Notification / Sample Request**

**Date:** May 08, 2020  
**To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team  
SC Business Services




**20200507000.1**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
ISO7730DWR	null
ISO7730FDWR	null
ISO7731DWR	null
ISO7731FDWR	null
ISO7740DWR	null
ISO7740FDWR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20200507000.1		<b>PCN Date:</b>	May 08, 2020				
<b>Title:</b>	Qualification of TI Malaysia as an additional Assembly site for Select Devices							
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services					
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Aug 08, 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request					
<b>Change Type:</b>								
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site			
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material			
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process			
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site			
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials			
				<input type="checkbox"/>	Wafer Fab Process			
<b>PCN Details</b>								
<b>Description of Change:</b>								
Texas Instruments is pleased to announce the qualification of TI Malaysia as an additional assembly site for the list of devices below. There are no construction differences between the current and new site.								
<b>Reason for Change:</b>								
Continuity of Supply								
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>								
None								
<b>Anticipated impact on Material Declaration</b>								
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>					
<b>Changes to product identification resulting from this PCN:</b>								
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>					
TI Taiwan	TAI	TWN	Chung Ho					
TI Malaysia	MLA	MYS	Kuala Lumpur					
Sample product shipping label (not actual product label)								
 MADE IN: Malaysia 2DC: 2Q: <table border="1" data-bbox="172 1659 571 1727"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 LBL: 5A (L)T0:1750		MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS	
MSL 2 /260C/1 YEAR	SEAL DT							
MSL 1 /235C/UNLIM	03/29/04							
<b>Product Affected:</b>								

ISO7730DW	ISO7731DWR	ISO7740FDW	ISO7741FBDWR
ISO7730DWR	ISO7731FBDW	ISO7740FDWR	ISO7741FDW
ISO7730FDW	ISO7731FBDWR	ISO7741BDW	ISO7741FDWR
ISO7730FDWR	ISO7731FDW	ISO7741BDWR	ISO7742DW
ISO7731BDW	ISO7731FDWR	ISO7741DW	ISO7742DWR
ISO7731BDWR	ISO7740DW	ISO7741DWR	ISO7742FDW
ISO7731DW	ISO7740DWR	ISO7741FBDW	ISO7742FDWR



## Qualification Report

Approve Date 30-Apr-2020

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>ISO7741FDW</u>	QBS Package Reference: <u>ISO1050DUB</u>
AC	Autoclave 121C	96 Hours	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	3/150/0
HTSL	High Temp Storage Bake 175C	500 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- QBS: Qual By Similarity
  - Qual Device ISO7741FDW is qualified at LEVEL2-260C
  - Device ISO7741FDW contains multiple dies.
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>  
Green/Pb-free Status:  
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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